

REMARKS/ARGUMENTS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 7-9 and 11 are pending in the present application. Claims 7-9 and 11 have been amended by the present amendment.

In the outstanding Office Action, Claims 7-9 and 11 were rejected under 35 U.S.C. § 103(a) as unpatentable over Chua et al. (U.S. Patent No. 6,825,553 B2, herein "Chua").

Applicant thanks the Examiner for the courtesy of an interview extended to Applicant's representative on May 9, 2006. During the interview, the differences between the claims and the applied art were discussed. Further, claim amendments clarifying the claims over the applied art were proposed by the Examiner and discussed. The present response sets forth those discussed claim amendments. The Examiner indicated she would further review the amended claims in view of a filed response. Arguments presented during the interview are reiterated below.

Regarding the rejection of Claims 7-9 and 11 under 35 U.S.C. § 103(a) as unpatentable over Chua, independent Claims 7-9 and 11 have been amended to recite that respective connecting members are electrically connected to probe pads and first test semiconductor chip elements. The claim amendments find support in Figure 1B and its corresponding description in the specification. No new matter has been added.

Briefly recapitulating, independent Claim 7 is directed to a semiconductor device that includes, *inter alia*, a first layer that has a plurality of first test semiconductor chip elements, and a second layer that has a plurality of probe pads. Connecting members are electrically connected to the first test semiconductor chip elements and the plurality of probe pads. Independent Claims 8, 9, and 11 have been amended similar to independent Claim 7.

In a non-limiting example, Figure 1B shows the first layer 20, the second layer 30, the first test semiconductor chip elements 22a, the probe pads 37, and the connecting members 34.

Turning to the applied art, Chua shows in Figure 3F a first layer 302, a second layer 310, a semiconductor dice 304 asserted to correspond to the claimed first test elements, a connection layer 304 asserted to correspond to the claimed pads, and solder balls 320 asserted to correspond to the claimed connecting members. However, as discussed during the interview, the semiconductor dice 304 and the connection layer 304 of Chua do not correspond to the claimed first test semiconductor chip elements and the probe pads as required by amended Claims 7-9 and 11.

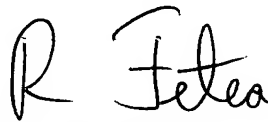
In addition, it is noted that the claimed corresponding connecting members electrically connect the first test semiconductor chip elements to the probe pads while the corresponding connecting members are not present in the second layer. On the contrary, the solder balls 320 of Chua are not connected to the dice 304. Even if one considers that a member 308 of Chua corresponds to the claimed connecting member, Applicant respectfully submits that the member 308 is present in both the first layer 302 and the second layer 310 in Chua, which is different from the claimed invention.

Accordingly, it is respectfully submitted that independent Claims 7-9 and 11 patentably distinguish over Chua.

Consequently, in light of the above discussion and in view of the present amendment, the present application is believed to be in condition for allowance and an early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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